



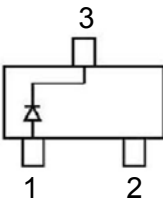
Features

- Planar Die Construction.
- 300mW Power Dissipation.
- Zener Voltages from 2.4V - 43V.
- Ultra-Small Surface Mount Package Power Dissipation



Package Marking and Ordering Information

Product ID	Pack	Brand	Qty(PCS)
BZX84-C15,215	SOT-23	HXY MOSFET	3000



Absolute Maximum Ratings(Ta=25°C)

Symbol	Parameter	Value	Unit
V _F	Forward Voltage (Note 2) @ I _F =10mA	0.9	V
P _d	Power Dissipationn (Note 1)	200	mW
R _{ΘJA}	Thermal Resistance From Junction To Ambient	625	°C/W
T _J	Operation Junction Temperature Range	-40~+125	°C
T _{STG}	Storage Temperature Range	-55~+150	°C

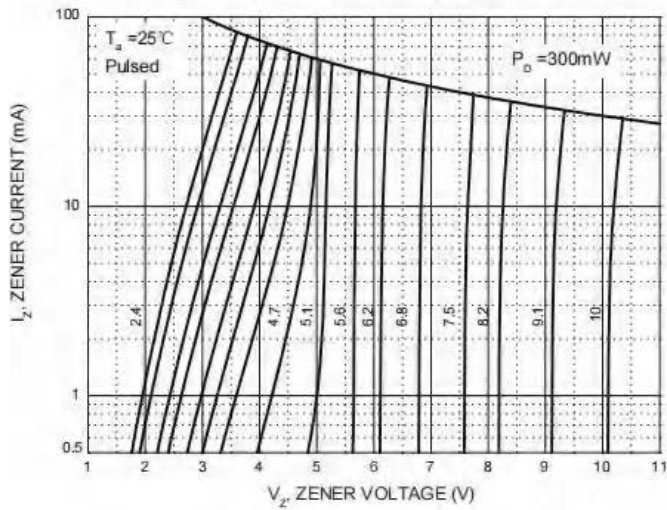
Electrical Characteristics (Ta=25°Cunless otherwise specified)

Type Number	Code	ZenerVoltage Range (Note 2)				Maximum Zener Impedance (Note 3)			Maximum Reverse Current		Temperature Coefficient of Zener voltage @ I _{ZT} =5mA mV/°C	
		V _Z @I _{ZT}			I _{ZT}	Z _{ZT} @I _{ZT}	Z _{ZK} @I _{ZK}	Z _K	I _R	V _R	Min	Max
		Nom(V)	Min(V)	Max(V)	(mA)	(Ω)		(mA)	(μA)	(V)		
BZX84-C15,215	Y4	15	13.8	15.6	5	30	200	1.0	0.1	10.5	9.2	13.0

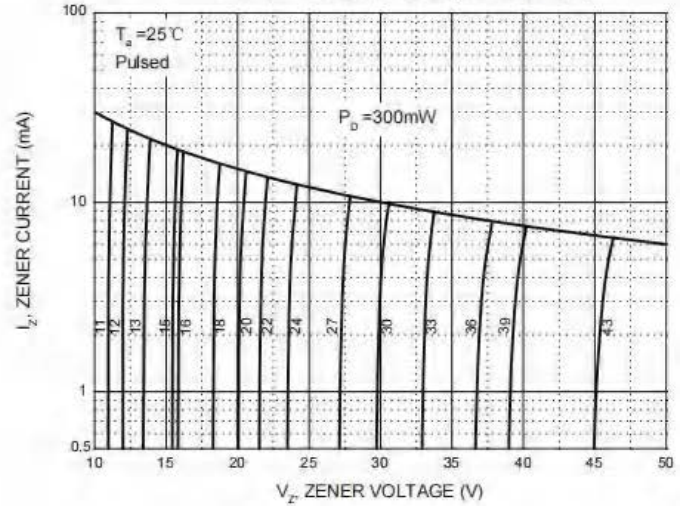


Typical Characteristics

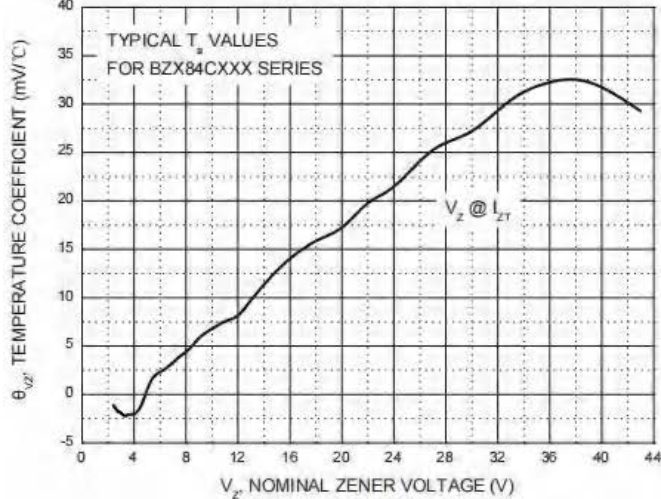
Zener Characteristics (V_Z Up to 10 V)



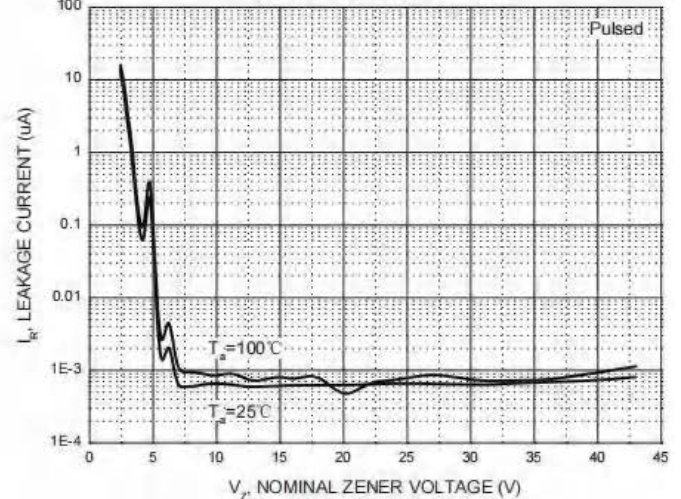
Zener Characteristics (11 V to 43 V)



Temperature Coefficients

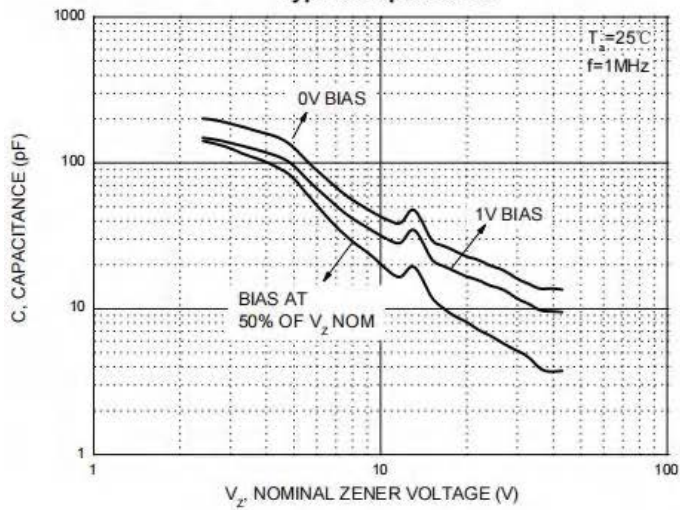


Typical Leakage Current

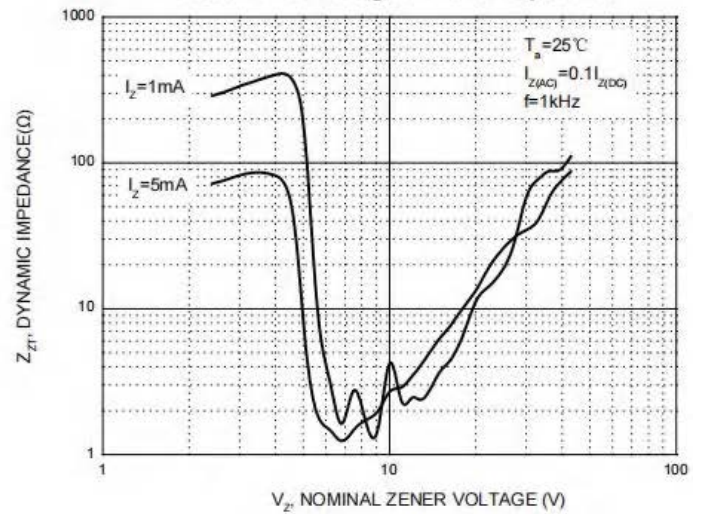




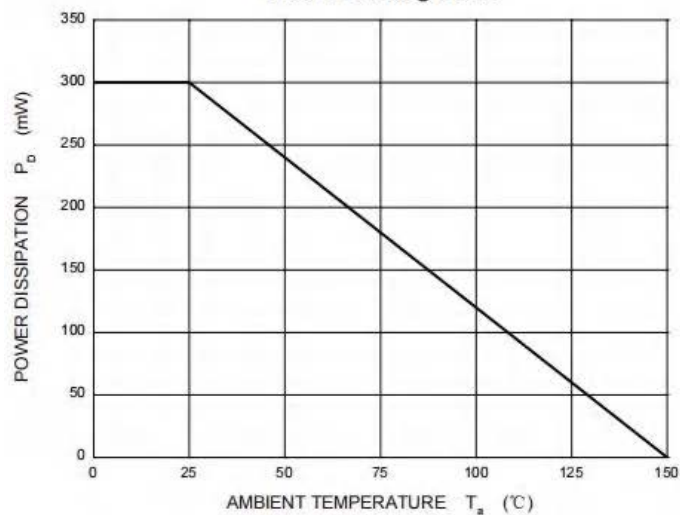
Typical Capacitance



Effect of Zener Voltage on Zener Impedance

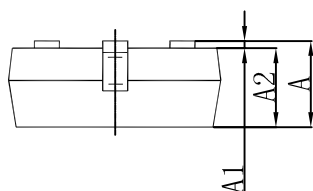
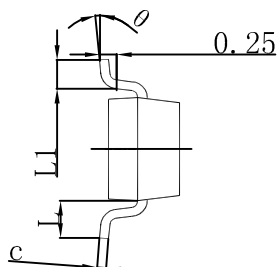
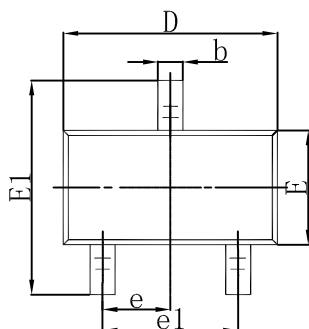


Power Derating Curve



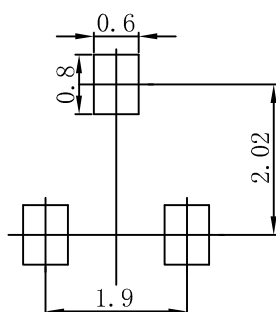


SOT-23 Package Outline Dimensions



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.900	1.150	0.035	0.045
A1	0.000	0.100	0.000	0.004
A2	0.900	1.050	0.035	0.041
b	0.300	0.500	0.012	0.020
c	0.080	0.150	0.003	0.006
D	2.800	3.000	0.110	0.118
E	1.200	1.400	0.047	0.055
E1	2.250	2.550	0.089	0.100
e	0.950 TYP		0.037 TYP	
e1	1.800	2.000	0.071	0.079
L	0.550 REF		0.022 REF	
L1	0.300	0.500	0.012	0.020
θ	0°	8°	0°	8°

SOT-23 Suggested Pad Layout



Note:

1. Controlling dimension: in millimeters.
2. General tolerance: $\pm 0.05\text{mm}$.
3. The pad layout is for reference purposes only.



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